IPC ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute					* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					ials and Mfg Information				
upplier Inform	ation														
Company name*			Company unique ID			ī	Unique ID Authority				Res	Response Date*			
nsemi										2025	2025-06-08				
Contact Name		Title - Contact			]	Phone - Contact*				Ema	Email - Contact*				
Product-Env-Stewa	ards		Product Enviro Compliance				NA				Pro	Product-Env-Stewards@onsemi.com			
uthorized Represe	ntative*	Title - Representative			1	Phone - Representative*				Ema	Email - Representative*				
Product-Env-Stewa	ırds	Product Enviro Compliance				NA				Pro	Product-Env-Stewards@onsemi.com				
Requeste	Requester Item Number Mfr Ite		tem Number Mfr Item Name				Effective Date   Version   N		Manufacturing Site We		Weight*	UOM	Unit Type		
		NRVBS3100T3G RECTIFIER 3A		RECTIFIER 3A 1	00V SURFAC	CE	2025-06-08			VN5		228.02	mg	Each	
	Proccess Information							•					·	•	
3			•		-STD-020 MS	SL Rating	Peak Process Body Tempera		<u> </u>	<u> </u>		perature Numb	er of Reflow Cy	cles	
Matte Tin (Sn) - annealed CU Alloy			CU Alloy	1			260		C	30	S	econds 3			
omments															
	ime at peak temperature														
or more informati	on regarding material co	mposition <b>j</b>	please refer t	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-6_								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.34	mg	Supplier	Silicon (Si)	7440-21-3		1.34	mg
Die Attach Solder	5.17	mg	Supplier	Silver (Ag)	7440-22-4		0.1293	mg
			A	Lead (Pb)	7439-92-1	7a	4.7822	mg
			Supplier	Tin (Sn)	7440-31-5		0.2585	mg
Lead Frame	92.28		Supplier	Zinc (Zn)	7440-66-6		0.1107	mg
			Supplier	Iron (Fe)	7439-89-6		2.1686	mg
			Supplier	Copper (Cu)	7440-50-8		89.973	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0277	mg
Mold Compound-Black	126.72		Supplier	Ortho Cresol Novolac Resin	29690-82-2		12.672	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6336	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		18.3744	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		82.368	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		12.672	mg
Plating	2.51	mg	Supplier	Tin (Sn)	7440-31-5		2.51	mg